



### **RPS 202TL-2**

## **Solderability Tester and Lead-Tinning System**

### **Features**

Meets all domestic and international specifications for solderability including ANSI-J-STD-002 and -003 for solderability testing

- Microprocessor controls
- PID temperature control
- Dual independently controlled solder baths
- Automatic fluxing
- Automatic dross wiper
- Programmable test sequence, depths, speeds, and times
- Optional Nitrogen inerting
- Optional Dynamic solder bath

### **Applications**

- Solderability testing components and PCB's
- Thermal shock components
- Dissolution of metalization testing
- Pre-tinning of components
- Programmable dipper for acid prep/cleaning and coating
- Evaluate alternate alloys

## **202TL-2** **Solderability Tester and Lead Tinning System**

### **Benefits**

Precise process control and repeatability

- Dual use system for test and production pre-tinning
- Large solder baths and smooth motion yields high pass rates
- Tool design and large solder baths combine for high productivity
- 2nd solder bath may be used for Gold scavenge, alternate alloys, or different temperatures

### **DESCRIPTION**

The 202TL-2 is a programmable dipper featuring two large solder baths and a flux station. The system will solderability test virtually any component and may be programmed for any sequence of operation such as:

Flux then solder bath #1 (single or double dip)

Flux then solder bath #1, flux, then solder bath #2 (single or double dip)

With the articulating end effector for quad /FP it will do any of the above sequences for the 2 or 4 quadrants

Immersion and immersion speeds, dwells, and positions are independently settable for each bath. The solder baths feature PID temperature controls and automatic dross wipers. The large capacity of the baths and supporting tooling make for a very efficient and productive system.

## Specifications

**Controller:** An intelligent micro-stepping motor drive system manages the 202TL-2. Easy to use programs are readily input or modified at the controller's keypad or via RS-232C serial interface. The abundant I/O controls auxiliary functions such as the optional rotary vacuum end effector or, Nitrogen. Up to 40 average length programs can be stored in the non-volatile memory. The controller features Help, Copy, Edit, Delete, and Jog capabilities.

- Non-volatile EE prom memory.
- Motor programmability. Motor "Z" vertical is regulated for high and low speeds, ramp-up and ramp-down varying speeds with a move. Up to 1411/sec. Travel, dwells down to 1 millisecond, and positioning to  $\pm .001$ "
- Joystick to job for set-up or adjusting programs.
- Eight bi-directional inputs/outputs
- PC compatible. RS232 port for use with integrated computerized factory.
- Interlocked for pot temperature and safety switches
- Auto home with seek and re-settable home positions.
- Linear interpolation

## Performance

**Configuration** Multi-station system with Dual (left/right) solder pots and central flux bath

**Operation** Automatic

**Accuracy** X-axis  $\pm .001$ "

Z-axis  $\pm .001$ "

**Repeatability**  $\pm .001$ "

**Programmability** Up to 40 individual programs

**Immersion Depth** Programmable in .001 steps

**Immersion Accuracy**  $\pm .001$ "

**Speed in/out** Infinitely programmable 0-6"/sec

**Immersion Time** Programmable in milliseconds

## Solder Pot

**Temperature control** PID proportioning  $(0-325^{\circ}\text{C}) \pm 2^{\circ}$

Note: Parameters are user settable, including process tolerance. If the solder temperature does not meet these set parameters, the equipment will not operate, thus eliminating the margin for operator error.

**Dimensions** 2" X 4" each vessel

**Capacity** 6 lbs. each vessel

**Flux** Static cascade overflow design

## Physical

Electrical 120vac/1ph/50-60hz/10amp

Dimension 36" x 22" x 16"

Weight 150 lbs.

## Options

- Nitrogen inerting system
- Dynamic solder bath
- Power transformer for 220v operation
- Crucibles
- Specialized tooling
- Articulating vacuum end effector for QFPs and flat Pak